



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSZ014NE2LS5IF	<b>Issued</b>	11. August 2021
<b>MA#</b>	MA005431900		
<b>Package</b>	PG-TSDSON-8-36	<b>Weight*</b>	35.68 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	1.76	1.76	17632	17632
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		103	
	non noble metal	zinc	7440-66-6	0.015	0.04		411	
	non noble metal	iron	7439-89-6	0.293	0.82		8216	
	non noble metal	copper	7440-50-8	11.903	33.36	34.23	333624	342354
wire	non noble metal	copper	7440-50-8	0.013	0.04	0.04	363	363
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		969	
	plastics	epoxy resin	-	1.590	4.46		44576	
	inorganic material	silicondioxide	60676-86-0	15.662	43.91	48.47	438975	484520
leadfinish	non noble metal	tin	7440-31-5	0.420	1.18	1.18	11785	11785
plating	noble metal	silver	7440-22-4	0.003	0.01	0.01	88	88
solder	noble metal	silver	7440-22-4	0.023	0.06		643	
	non noble metal	tin	7440-31-5	0.046	0.13		1286	
	non noble metal	lead	7439-92-1	0.849	2.38	2.57	23789	25718
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		141	
	non noble metal	iron	7439-89-6	0.101	0.28		2821	
	non noble metal	copper	7440-50-8	4.087	11.45	11.74	114543	117540
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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